

What is claimed is:

- 1 1. An apparatus for dissipating heat from an electronic device, the apparatus
2 comprising:
3 a housing adapted to be closely fitted to a heat sink; the housing having a
4 first end and a second end; and
5 an air moving device adapted to be coupled to a first end of the housing, the
6 air moving device to move air through the housing.
- 1 2. The apparatus of claim 1 further comprising an air duct coupled ^{202 (205)} ^{to} the second
2 end of the housing, the air duct to direct the flow of air from an exterior of a chassis
3 to the housing.
- 1 3. The apparatus of claim 2 wherein the air duct is a flexible hose.
- 1 4. The apparatus of claim 3 wherein the air duct is an extendable hose.
- 1 5. The apparatus of claim 2 wherein the air duct is rigid.
- 1 6. The apparatus of claim 1 wherein the air moving device is a fan.
- 1 7. The apparatus of claim 6 wherein the fan has a diameter of between about 20
2 millimeters and about 120 millimeters.
- 1 8. The apparatus of claim 6 wherein the fan has a diameter of about 60
2 millimeters.
- 1 9. The apparatus of claim 6 wherein the fan is coupled to the housing at a
2 distance from the heat sink that is about equal to a diameter of the fan.

1 10. The apparatus of claim 6 wherein the fan is coupled to the housing at a
2 distance from the heat sink that is less than a diameter of the fan.

1 11. An integrated circuit cooling system comprising:
2 means to generate a flow of air through a plurality of fins of a heat sink; and
3 means to contain and guide air movement through the plurality of fins of the
4 heat sink wherein the means to contain and guide air movement substantially
5 eliminates blowby.

1 12. The integrated circuit cooling system of claim 11 further comprising means
2 to direct air external to a chassis to the means to contain and guide air movement.

1 13. The integrated circuit cooling system of claim 11 wherein the means to
2 generate a flow of air exhausts the means to contain and guide air movement.

1 14. The integrated circuit cooling system of claim 10 wherein the means to
2 generate a flow of air pressurizes the means to contain and guide air movement.

1 15. A computerized system comprising:
2 a chassis;
3 an integrated circuit board mounted in the chassis;
4 a processor coupled to the integrated circuit board; and
5 a processor cooling system coupled to the processor, the processor cooling
6 system comprising:
7 a heat sink coupled to the processor;
8 a housing coupled to the heat sink, the housing positioned in close
9 proximity to the heat sink; and
10 a fan coupled to the housing, the fan to create a flow of air through
11 the housing.
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1 16. The computerized system of claim 15 further comprising a first air duct
2 coupled to the housing and to the chassis, the air duct to channel external ambient
3 air to the heat sink.

1 17. The computerized system of claim of claim 16 further comprising a second
2 air duct coupled to the housing and to the chassis, the second air duct to channel
3 heated air away from the heat sink and out of the chassis.



The computerized system of claim 15 further comprising:
a second fan coupled to the housing; and
an air duct coupled to the housing.

1 19. The computerized system of claim 15 further comprising:
2 a second processor coupled to the integrated circuit board;
3 a second heat sink coupled to the second processor;
4 a second housing coupled to the second heat sink, the second housing
5 positioned in close proximity to the second heat sink;
6 a second fan coupled to the second housing; and
7 a housing connector coupled to the first housing and the second housing.

1 20. A method of assembling a cooling system for an integrated circuit, the
2 method comprising:
3 closely coupling a housing to a heat sink for an integrated circuit; and
4 coupling a fan to the housing

1 21. The method of claim 20 further comprising coupling one or more cooling
2 attachments to the housing.
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1 22. The method of claim 21 wherein coupling one or more cooling attachments
2 to the housing comprises coupling an air duct to the housing and to a chassis.

1 23. The method of claim 22 further comprising coupling a cooling attachment to
2 the fan.23.

1 24. The method of claim 23 wherein coupling a cooling attachment to the fan
2 further comprises coupling an extendable, flexible hose to the fan and to the chassis.

1 25. A method of cooling an integrated circuit, the method comprising:
2 generating a flow of external ambient air through an air duct to a housing
fitted closely over a heat sink; and
drawing the flow of external ambient air over the heat sink.

1 26. The method of claim 25 further comprising drawing the flow of external
2 ambient air over the second heat sink positioned in-line with the first heat sink.

1 27. The method of claim 25 further comprising exhausting heated air drawn over
2 the first heat sink and the second heat sink into a chassis.

1 28. A kit of parts for an electronic component cooling system, the kit
2 comprising:
3 one or more heat sink housings adapted to fit over a heat sink for an
4 electronic component; and
5 a plurality of interchangeable cooling attachments adapted to be combined
6 with the one or more heat sink housings to form an electronic component cooling
7 system.

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1 29. The kit of parts as claimed in claim 28 further comprising a fan adapted to be
2 coupled to the one or more heat sink housings.

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4 30. The kit of parts as claimed in claim 28 wherein the plurality of cooling
5 attachments are selected from the group consisting of: a housing air duct adapter, an
6 air inlet chassis adapter, a housing fan adapter, a housing connector, a chassis fan
7 adapter, and a splitter.